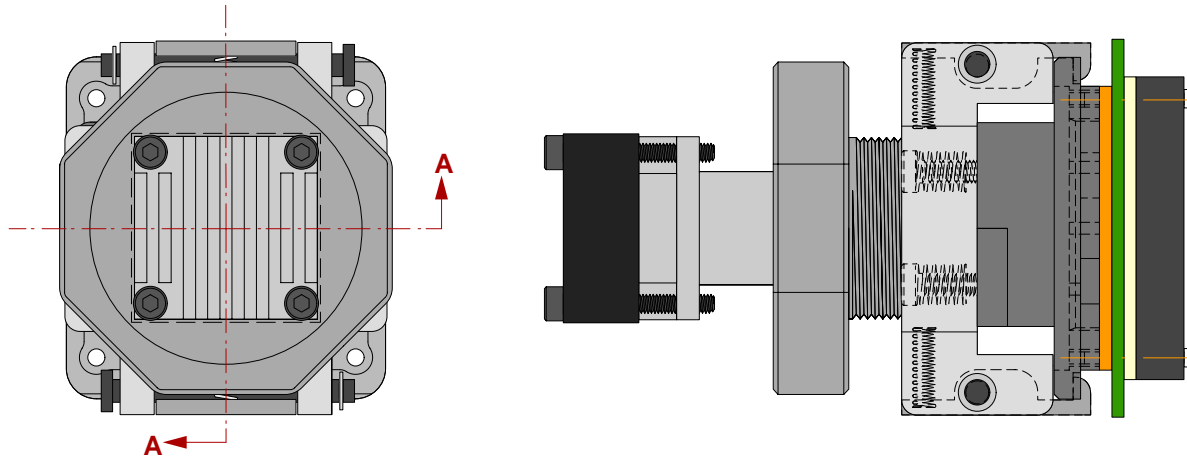
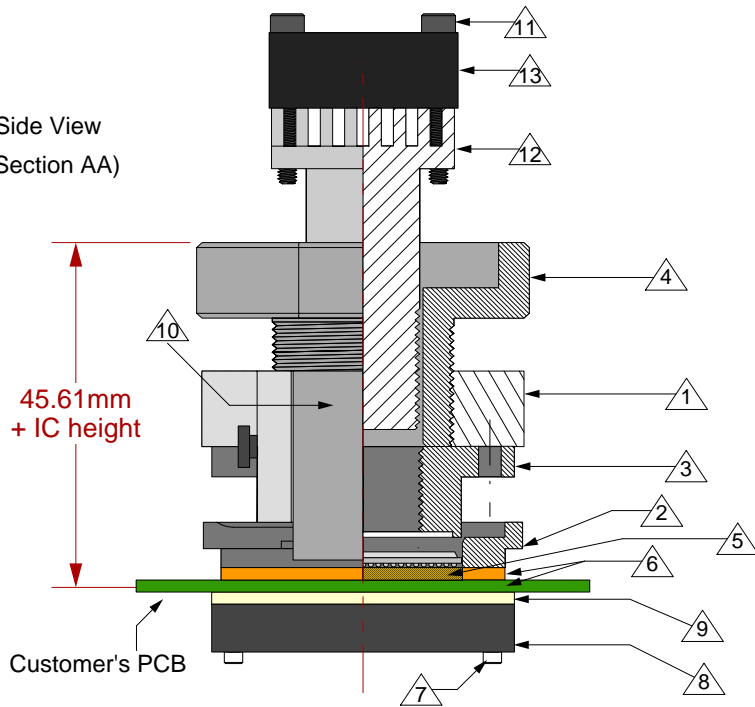


Top View



Side View
(Section AA)




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

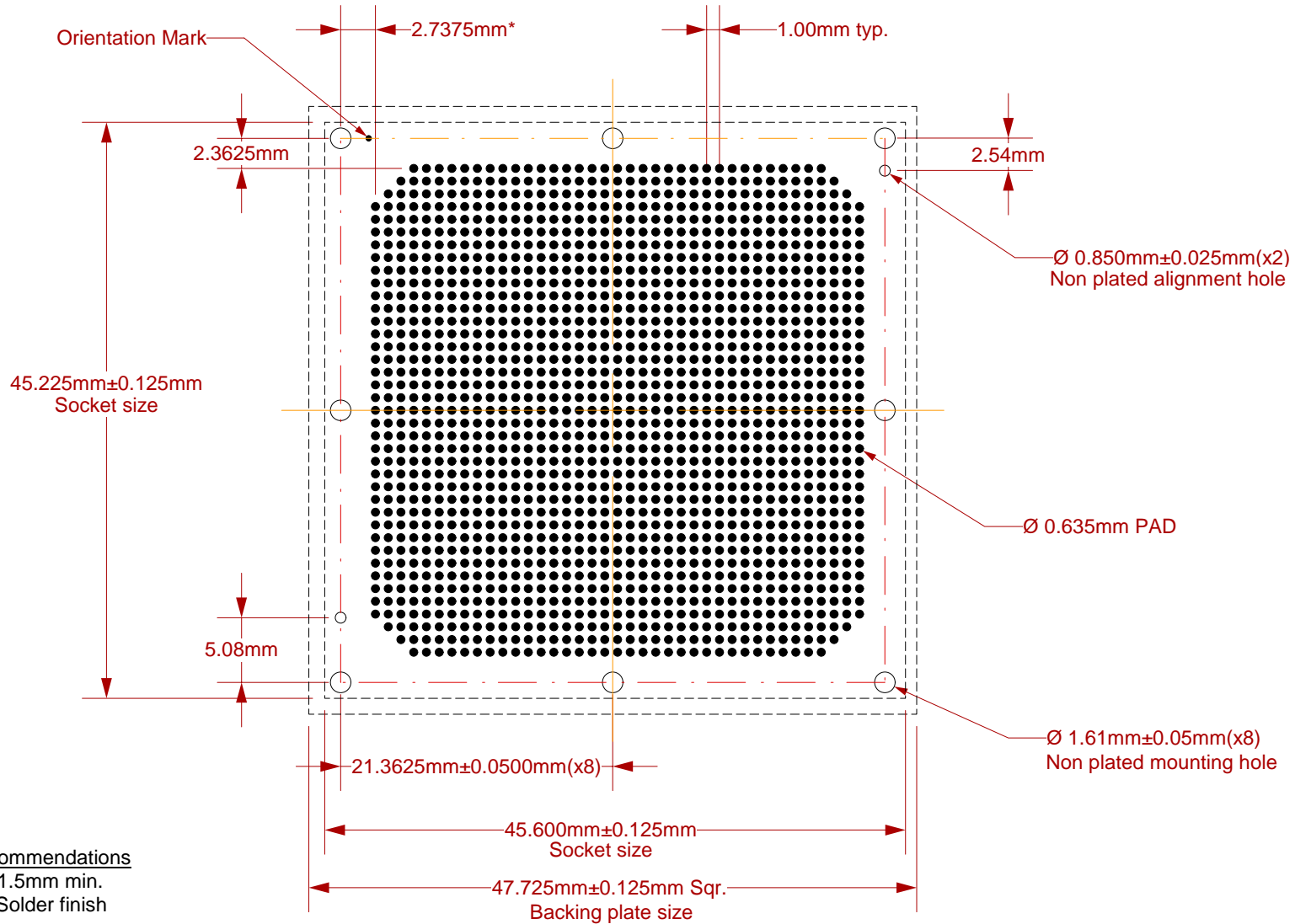
Materials:

- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.75mm.
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Latch: Black anodized Aluminum.
- 11 Fan screw: M4 size 16mm length 0.7mm pitch
- 12 Heatsink: Aluminum
- 13 Fan: 50mmX50mmX10mm, 5V 12.3 CFM

	CG-BGA-4000 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 01/11/08	
		File: CG-BGA-4000 Dwg	Modified:	

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.


***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



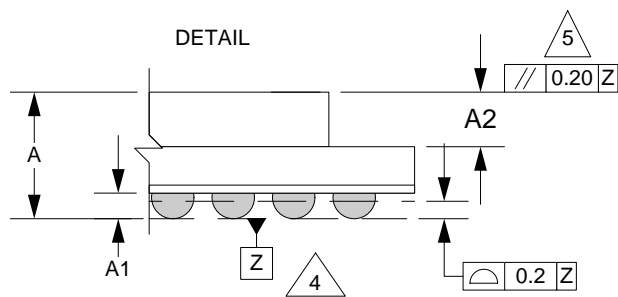
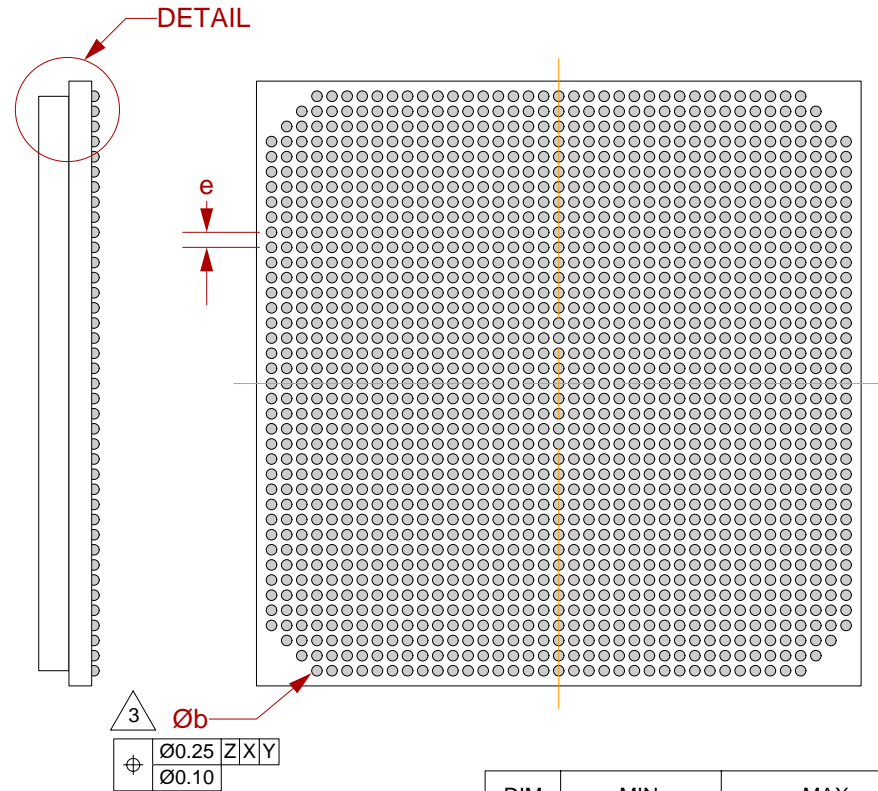
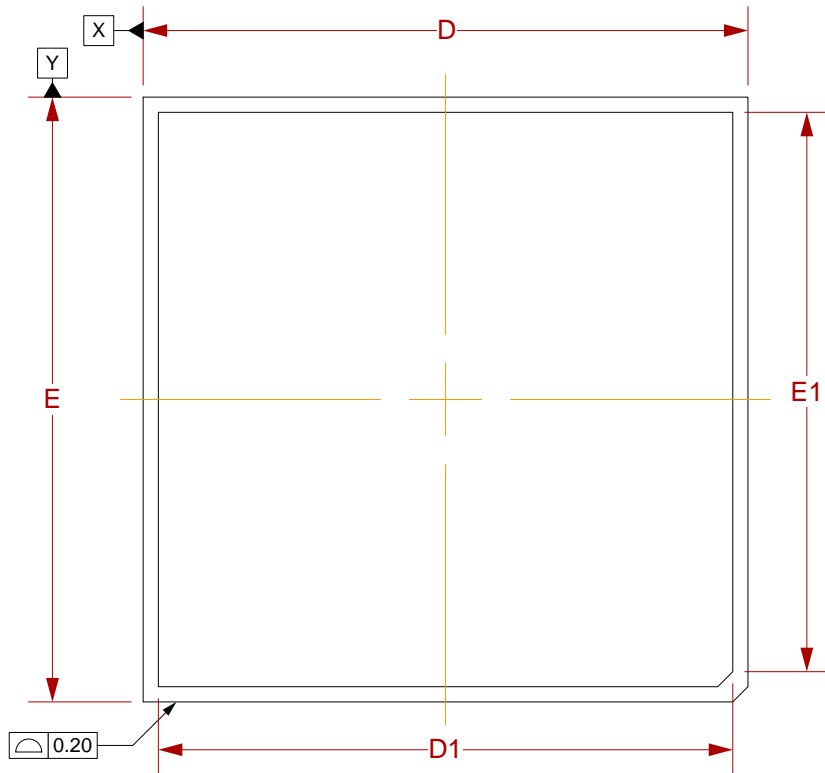
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

	CG-BGA-4000 Drawing		Status: Released	Scale: 3:1	Rev: A
	© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com		Drawing: J. Glab		Date: 01/11/08
			File: CG-BGA-4000 Dwg		Modified:

Compatible BGA Spec




1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

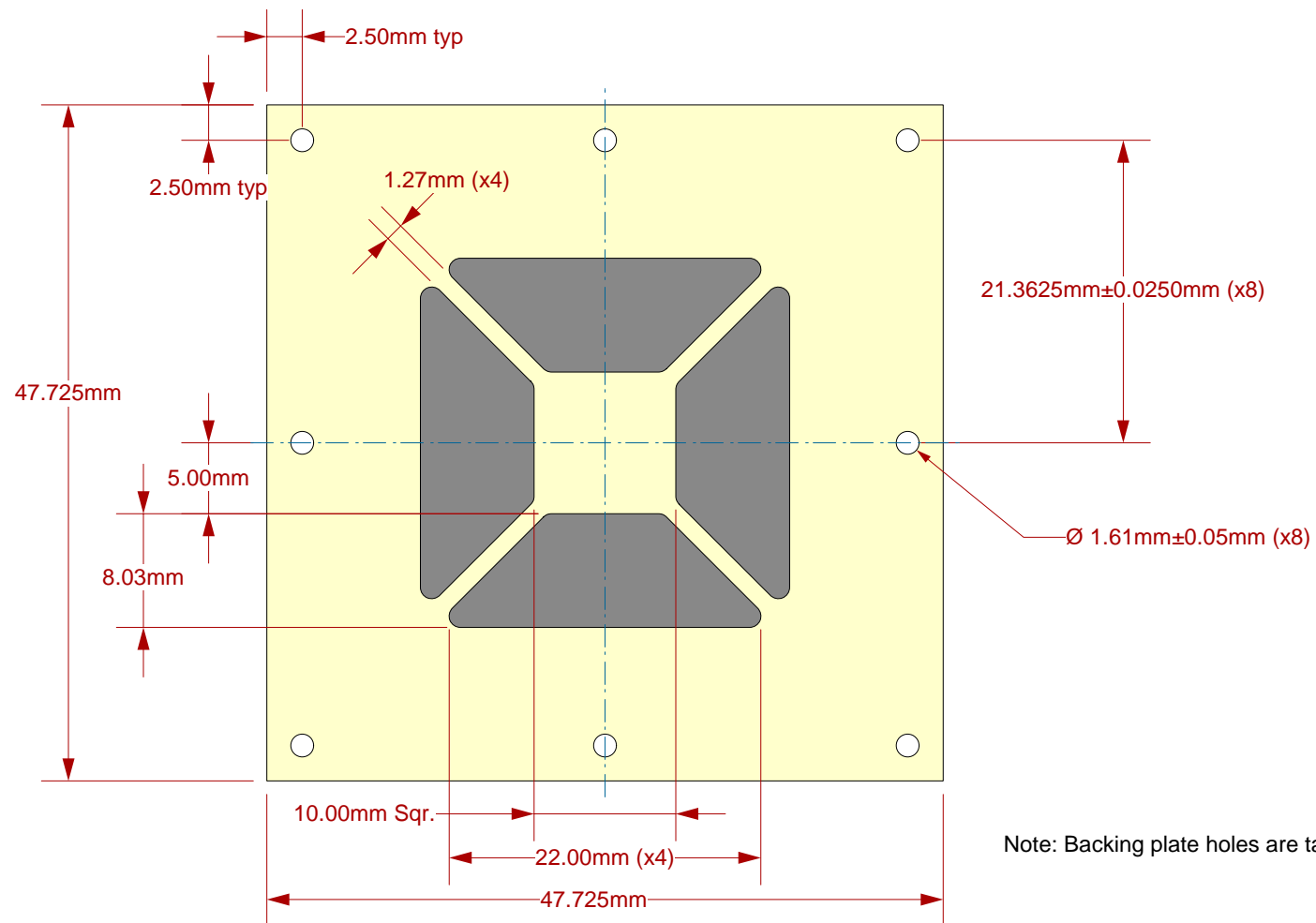
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		4.0
A1	0.4	0.6
A2		1.9
b		0.70
D	40.00 BSC	
D1	38.0	
E	40.00 BSC	
E1	38.0	
e	1.0 BSC	

39x39 Array

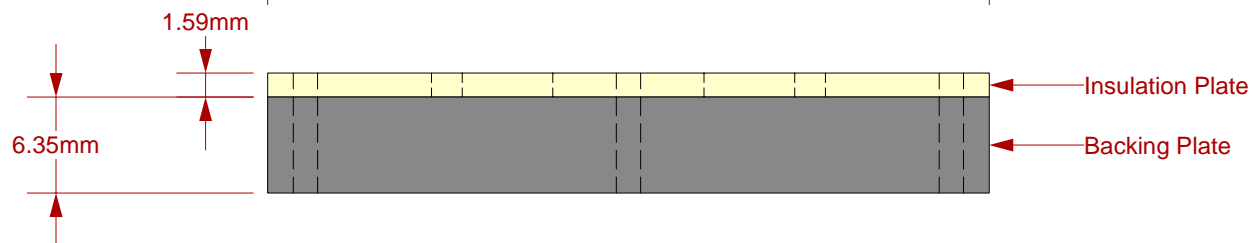
 <p>© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>CG-BGA-4000 Drawing</p>	<p>Status: Released</p>	<p>Scale: -/-</p>	<p>Rev: A</p>
	<p>Drawing: J. Glab</p>	<p>Date: 01/11/08</p>		
	<p>File: CG-BGA-4000 Dwg</p>	<p>Modified:</p>		

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

	CG-BGA-4000 Drawing	Status: Released	Scale: 1.25:1	Rev: A
	© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 01/11/08	
		File: CG-BGA-4000 Dwg	Modified:	